**Automatic Surface Grinder**

**DAG810**

Automatic grinding for research and production

**Single-axis automatic grinder**
The DAG810 is a compact, automatic grinder for workpieces up to 8" in diameter. It has one spindle and one chuck table and is designed to process a variety of materials.

**Small footprint – 1.02 m²**
Machine dimensions: 600 (W) x 1,700 (D) x 1,780 (H) mm

**Precision grinding**
The newly developed high-rigidity, low-vibration spindle achieves superior grinding results and is capable of in-feed grinding and creep feed grinding (user-specified specification).

**Unlimited materials**
Process hard or brittle substrates of various diameters with ease. The DAG810 is also the choice for processing a wide variety of electronic components.

**Easy operation**
The LCD touch screen graphical user interface makes operation both intuitive and easy.

**Special options for a variety of needs**
- Can be equipped with either one or two probe-height gauges (option)
- In-feed grinding for workpieces up to ø300 mm (option)
- 8" frame grinding (option)
- Creep-feed grinding for workpieces up to ø200 mm in diameter (user-specified specification)

**High-precision applications**
- Processes silicon and compound semiconductors for analysis.
- Grinds resin for CSP and WL-CSP
- Performs copper-post exposure and other metal applications
- Improves the planarity of lithium tantalate and lithium niobate
- Processes green ceramics and sapphire (small diameter)
**Specifications**

<table>
<thead>
<tr>
<th>Specification</th>
<th>Unit</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>Wafer Diameter</td>
<td>mm</td>
<td>( \phi 200 ) (( \phi 4&quot;/5&quot;/6&quot;/8&quot; ) with universal chuck table use)</td>
</tr>
<tr>
<td>Grinding Method</td>
<td>-</td>
<td>Anomalous In-feed grinding with wafer rotation</td>
</tr>
<tr>
<td>Grinding Wheels</td>
<td>mm</td>
<td>( \Phi 200 ) Diamond Wheel</td>
</tr>
<tr>
<td>Spindle Output</td>
<td>kW</td>
<td>4.2</td>
</tr>
<tr>
<td>Rated torque</td>
<td>N( \cdot )m</td>
<td>5.9</td>
</tr>
<tr>
<td>Revolution speed range</td>
<td>min(^{-1})</td>
<td>1,000 - 7,000</td>
</tr>
<tr>
<td>Machine dimensions(W×D×H)</td>
<td>mm</td>
<td>600 × 1,700 × 1,780</td>
</tr>
<tr>
<td>Machine weight</td>
<td>kg</td>
<td>Approx.1,300</td>
</tr>
</tbody>
</table>

**Environmental conditions**

- Use clean, oil-free air at a dew point of –15 °C or less. (Use a residual oil: 0.1 ppm, Filtration rating: 0.01 µm/99.5 % or more).
- Keep room temperature fluctuations within ±1 °C of the set value. (Set value should be between 20 – 25 °C).
- Keep grinding water at 0 – 2 °C above room temperature (fluctuations within 1 °C over one hour).
- Keep spindle cooling water temperature between 20 – 25 °C (fluctuations within 2 °C over an hour).
- The machines should be used in an environment, free from external vibration. Do not install machine near a ventilation opening, heat generation equipment or oil mist generating parts.
- This machine uses water. In case of water leakage, please install the machine on the floor with sufficient waterproofing and drainage treatments.
- All the pressures are described using gauge pressure.
- The above specifications may change due to technical modifications. Please confirm when placing your order.
- For further information please contact your local sales representatives.
- When you use it anything other than the deionized water, please contact your local representatives.